

METHOD FOR MAKING INK JET PRINTHEADS

Abstract Of The Disclosure

The invention provides an improved method for grit blasting slots in a silicon wafer. The method includes, providing a silicon wafer having a first surface and a second surface, the first surface containing resistive, conductive and insulative layers
5 defining individual semiconductor components, applying a first substantially permanent non-water soluble layer selected from silane, photoresist materials and a combination of a silane layer and a photoresist layer to the first surface of the wafer to provide a first substantially permanent layer thereon, applying a water-soluble protective material to the first layer to provide a second layer, grit blasting slots in the wafer corresponding to the
10 individual semiconductor components, and subsequently, removing the water-soluble protective layer from the wafer. The protective layer provides enhanced protection for the electrical components on a silicon wafer during a grit blasting process so that a higher yield of useable semiconductor chips may be made.